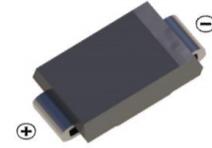
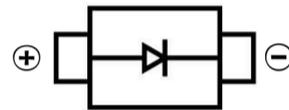


## Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250 °C/10 seconds at terminals



DO-214AB/SMC



## Mechanical Data

Case : JEDEC DO-214AB/SMC molded plastic body  
 Terminals : Solderable per MIL-STD-750, Method 2026  
 Polarity : Color band denotes cathode end Mounting  
 Position : Any  
 Weight : 0.0077ounce, 0.22 grams

## Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS52C	SS53C	SS54C	SS55C	SS56C	SS58C	SS510C	SS5150C	SS5200C	UNITS	
Marking Code												
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	80	100	150	200	V	
Maximum RMS voltage	$V_{RMS}$	14	21	28	35	42	56	70	105	140	V	
Maximum DC blocking voltage	$V_{DC}$	20	30	40	50	60	80	100	150	200	V	
Maximum average forward rectified current	$I_{(AV)}$	5.0									A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	175					150					A
Maximum instantaneous forward voltage at 5.0A	$V_F$	0.55			0.70			0.85			V	
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	1.0					50					mA
Typical junction capacitance (NOTE 1)	$C_J$	600			400						pF	
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	35									$^\circ\text{C}/\text{W}$	
Operating junction temperature range	$T_J$	-55 to +125					-55 to +150					$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150									$^\circ\text{C}$	

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. P.C.B. mounted with 2.0"x2.0" (5.0x5.0cm) copper pad areas

## Typical Characteristics

Fig.1 Forward Current Derating Curve

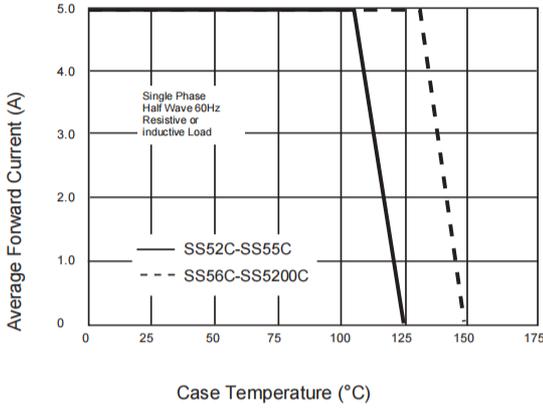


Fig.2 Typical Reverse Characteristics

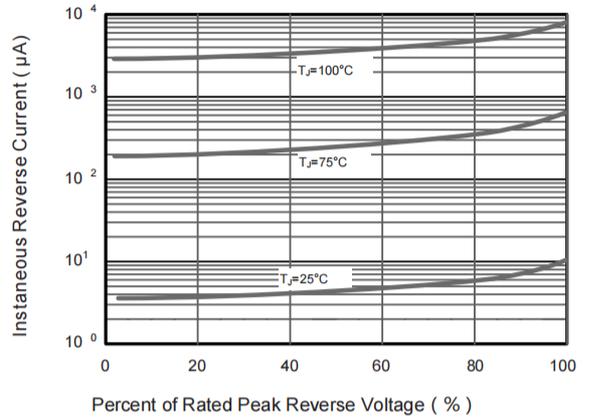


Fig.3 Typical Forward Characteristic

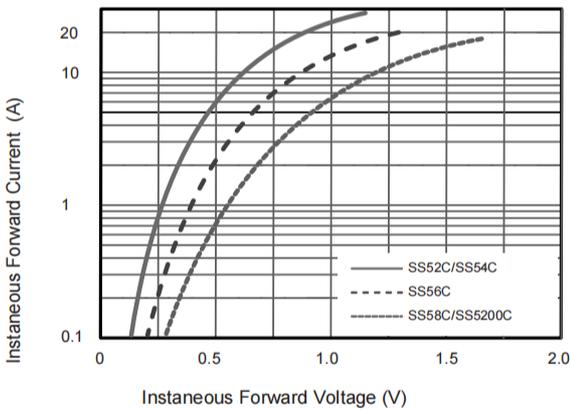


Fig.4 Typical Junction Capacitance

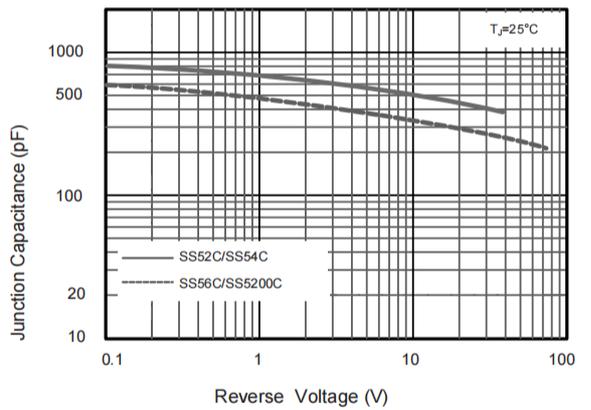


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

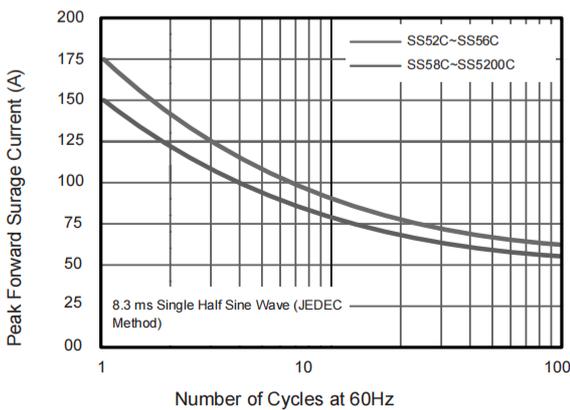
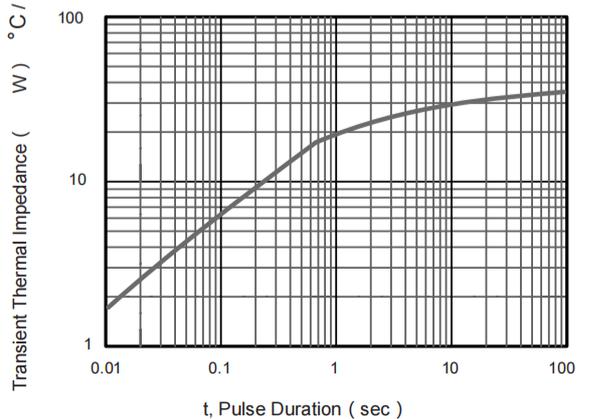
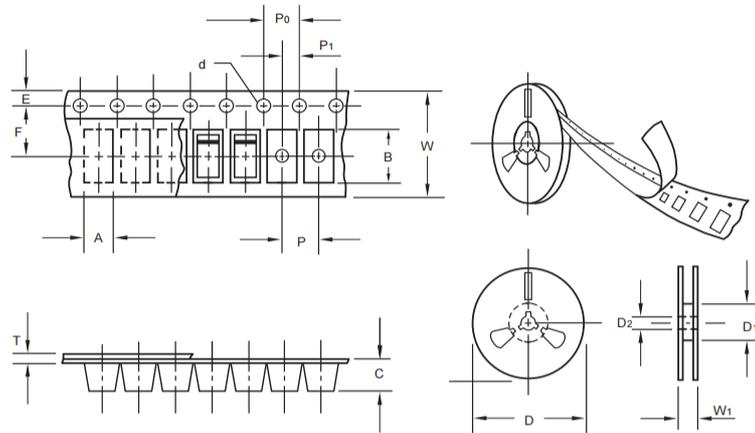


Fig.6- Typical Transient Thermal Impedance



## Packing information

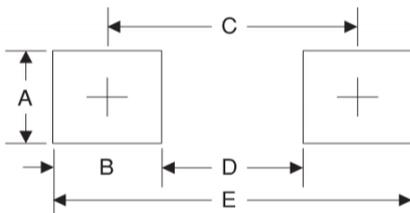


unit:mm

Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W <sub>1</sub>	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472